SCHS105A - Revised March 2002

# CD40175B Types

# CMOS Quad 'D'-Type Flip-Flop

#### High-Voltage Types (20-Volt Rating)

#### Features:

- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full packagetemperature range; 100 nA at 18 V and 25° C
- Noise margin (full packagetemperature range) =
  - 1 V at VDD = 5 V 2 V at VDD = 10 V
- 2.5 V at VDD = 15 V

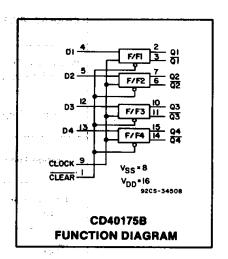
  5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

SHIP BURSHING ST

- Output compatible with two HTL loads, two low power TTL loads, or one low power Schottky TTL load
- Functional equivalent to TTL 74175
- Standardized symmetrical output characteristics

#### **Applications:**

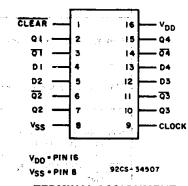
- Shift registers
- Buffer/storage registers
- Pattern generators



CD40175B consists of four identical D-type flipflops. Each flip-flop has an independent DATA D input and complementary Q and Q outputs. The CLOCK and CLEAR inputs are common to all flip-flops. Data are transferred to the Q outputs on the positive-going transition of the clock pulse. All four flip-flops are simultaneously reset by a low level on the CLEAR input.

These devices can function as shift register elements or as T-type flip-flops for toggle and counter applications.

The CD40175B is supplied in hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline package (NSR suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).



#### **TERMINAL ASSIGNMENT**

MAXIMUM RATINGS, Absolute-Maximum Values:  DC SUPPLY-VOLTAGE RANGE, (VDD)  Voltages referenced to VSS Terminal)  -0.5V to +20V  INPUT VOLTAGE RANGE, ALL INPUTS  -0.5V to VDD +0.5V  DC INPUT CURRENT, ANY ONE INPUT  +10mA  POWER DISSIPATION PER PACKAGE (PD):  For TA = -55°C to +100°C  For TA = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)  100mW  OPERATING-TEMPERATURE RANGE (Tat)  -55°C to +125°C  STORAGE TEMPERATURE RANGE (Tatg)  -65°C to +150°C  LEAD TEMPERATURE (DURING SOLDERING):  At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max  +265°C	MAXIMUM RATINGS, Absolute-Maximum Values:	247	. * - *		
INPUT VOLTAGE RANGE, ALL INPUTS  DC INPUT CURRENT, ANY ONE INPUT  \$\frac{\text{tomA}}{\text{power}}\$  \$\text{POWER DISSIPATION PER PACKAGE (PD):}{\text{For T}_{\text{A}} = -55^{\text{oc}} \text{to } \text{to } \text{to } \text{to } \text{2500mW} \text{For T}_{\text{A}} = \text{to } \text{to } \text{to } \text{to } \text{to } \text{200mW} \text{DEVICE DISSIPATION PER OUTPUT TRANSISTOR}   \$\text{FOR T}_{\text{A}} = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)} \text{100mW}   \$\text{OPERATING-TEMPERATURE RANGE (Tatg)} \text{-5500c to } \text{+12500c}   \$\text{STORAGE TEMPERATURE RANGE (Tatg)} \text{-6500c to } \text{+15000c}   \$\text{LEAD TEMPERATURE (DURING SOLDERING):} \text{100mW}	DC SUPPLY-VOLTAGE RANGE, (VDD)	w <sub>1</sub> .	**		
INPUT VOLTAGE RANGE, ALL INPUTS  DC INPUT CURRENT, ANY ONE INPUT  \$\frac{\text{tomA}}{\text{power}}\$  \$\text{POWER DISSIPATION PER PACKAGE (PD):}{\text{For T}_{\text{A}} = -55^{\text{oc}} \text{to } \text{to } \text{to } \text{to } \text{2500mW} \text{For T}_{\text{A}} = \text{to } \text{to } \text{to } \text{to } \text{to } \text{200mW} \text{DEVICE DISSIPATION PER OUTPUT TRANSISTOR}   \$\text{FOR T}_{\text{A}} = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)} \text{100mW}   \$\text{OPERATING-TEMPERATURE RANGE (Tatg)} \text{-5500c to } \text{+12500c}   \$\text{STORAGE TEMPERATURE RANGE (Tatg)} \text{-6500c to } \text{+15000c}   \$\text{LEAD TEMPERATURE (DURING SOLDERING):} \text{100mW}	Voltages referenced to VSS Terminal)				0.5V to +20V
DC INPUT CURRENT, ANY ONE INPUT  +10mA  POWER DISSIPATION PER PACKAGE (PD):  For TA = -55°C to +100°C  For TA = +100°C to +125°C  Derate Linearity at 12mW/°C to 200mW  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)  OPERATING-TEMPERATURE RANGE (TA)  STORAGE TEMPERATURE RANGE (Tatg)  -65°C to +150°C  LEAD TEMPERATURE (DURING SOLDERING):	INPUT VOLTAGE RANGE, ALL INPUTS				0.5V to V <sub>DD</sub> +0.5V
For T <sub>A</sub> = -55°C to +100°C					
For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)  OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )  STORAGE TEMPERATURE RANGE (T <sub>atg</sub> )  LEAD TEMPERATURE (DURING SOLDERING):	POWER DISSIPATION PER PACKAGE (Po):				
For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)  OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )  STORAGE TEMPERATURE RANGE (T <sub>atg</sub> )  LEAD TEMPERATURE (DURING SOLDERING):					
DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)	For $T_A = -55^{\circ}C$ to $+100^{\circ}C$				500mW
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package-Types)	For $T_A = -55^{\circ}C$ to $+100^{\circ}C$			Derate Linear	500mW ity at 12mW/°C to 200mW
OPERATING-TEMPERATURE RANGE (T <sub>A</sub> ) -55°C to +125°C STORAGE TEMPERATURE RANGE (T <sub>Stg</sub> ) -65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING):	For T <sub>A</sub> = -55°C to +100°C		**************************************	Derate Linear	ity at 12mW/°C to 200mW
LEAD TEMPERATURE (DURING SOLDERING):	For T <sub>A</sub> = -55°C to +100°C  For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All	Package Types).	TO Be a reading to the second	Derate Linear	ity at 12mW/°C to 200mW
LEAD TEMPERATURE (DURING SOLDERING):	For T <sub>A</sub> = -55°C to +100°C  For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All	Package Types).	TO Be a reading to the second	Derate Linear	ity at 12mW/°C to 200mW
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	For T <sub>A</sub> = -55°C to +100°C  For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (AII  OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )	Package Types).	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	Derate Linear	ity at 12mW/°C to 200mW 100mW 55°C to +125°C
	For T <sub>A</sub> = -55°C to +100°C  For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (AII  OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )  STORAGE TEMPERATURE RANGE (T <sub>atg</sub> )  LEAD TEMPERATURE (DURING SOLDERING):	Package-Types).	To a control of the c	Derate Linear	ity at 12mW/°C to 200mW100mW55°C to +125°C65°C to +150°C

#### RECOMMENDED OPERATING CONDITIONS at TA = 25°C, Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CUADACTERIO		LIN			
CHARACTERISTIC	Vod (V)	MIN.	MAX.	UNITS	
Supply-Voltage Range (For TA = Full Package-Temperature Range)		3	18	1 . 1 V	
	5 .	120			
Data Setup Time tsu	10	50	–	ns	
	15	40	-	1	
	5	80	_		
Data Hold Time th	10	40	_	ns	
	15	30	_		
	5	_	2	1.5	
Clock Input Frequency fcL	10	dc	5	MHz	
en e	15	_	6.5		
	5	<del>-</del>	15		
Clock Input Rise or Fall Time trcL, trcL	10	· <b>–</b>	15	μs	
	15	<u> </u>	15		
	5	250	-		
Clock Input Pulse Width twL, twH	10	100	_	ns	
	15	75			
	5	200			
Clear Pulse Width twL	10	80	_	ns	
	15	60	_		
	5	250		1	
Clear Removal Time trem	10	100	_	ns	
	15	80	_		

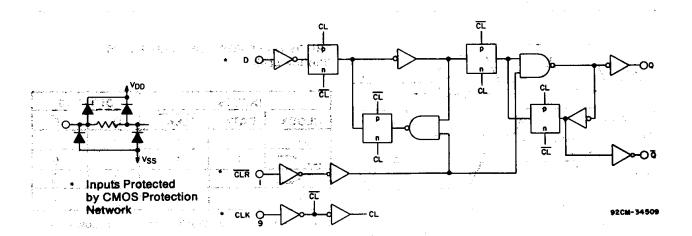


Fig. 1 - Logic diagram (1 of 4 flip-flops).

#### STATIC ELECTRICAL CHARACTERISTICS

CHARACTERIS	co	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS	
		Vo	Vin	VDD						+25		
		(V)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent			0, 5	5	1	1	30	30	-	0.02	1	
Device			0, 10	10	2	2	60	60	_	0.02	2	1.
Current		_	0, 15	15	4	4	120	120	_	0.02	4	μΑ
Max.	DD	_	0, 20	20	20	20	600	600		0.04	20)	
Output Low		0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	_	
(Sink) Current		0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	
Min.	IOL	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	_	1
Output High		4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		mA
(Source)		2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	]
Current		9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_	1
Min.	Юн	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	
Output Voltage:			0, 5	5		Ō.	05			0	0.05	<b>†</b>
Low-Level		_	0, 10	10		0.	05		_	0	0.05	1
Max.	VOL	-	0, 15	15		O.	05		_	0	0.05	1
Output Voltage:		_	0, 5	5		4.	95		4.95	5	_	v
High-Level			0, 10	10	†	9.	95		9.95	10	<u> </u>	1
Min.	Vон		0, 15	15	14.95			14.95	15		1	
Input Low	••••	0.5,4.5	_	5		1	.5		_	_	1.5	
Voltage		1, 9	_	10		;	3		_	_	3	1
Max.	VIL	1.5,13.5		15			4		-	_	4	
Input High		0.5,4.5		5	İ	3	.5		3.5	_	_	V
Voltage		1, 9	_	10		•	7		7	<del></del>	_	
Min.	Vін	1.5,13.5	_	15	1.1			11.			1	
Input Current Max	c. lin	_	0, 18	18	±0.1	±0.1	±1	±1	_	±10-5	±0.1	μΑ

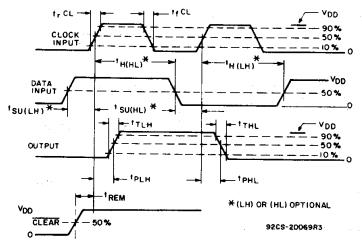


Fig. 2 - Definition of setup, hold, propagation delay, and removal times.

# TRUTH TABLE FOR 1 OF 4 FLIP-FLOPS (Positive Logic)

	INPUTS	OUTPUTS			
CLOCK	DATA	CLEAR	Q	la	
	0	1	0	1	
	1	1	1	0	
	Х	1	Q	ব	
Х	Х	0 50 200	0	1	

1=High Level X=Don't Care 0=Low Level

#### DYNAMIC ELECTRICAL CHARACTERISTICS at TA = 25° C; Input tr, tr = 20 ns, CL = 50 pF, RL = 200 k $\Omega$

			:		
CHARACTERISTIC	TEST CONDITIONS VDD (V)	MIN.	TYP.	MAX.	UNITS
	5		100	200	
Transition Time tthe, tteh	10		50	100	
	15	<b>–</b>	40	80	_
Propagation Delay Time	5	- <u>-</u> -	220	400	
Clock to Q Output tPHL, tPLH	10	<b></b> .	90	160	
•	15	_	70	120	
Propagation Delay Time	5	_	325	500	7
CLEAR to Q Output tPHL	10		130	200	ns
	15		100	150	
Minimum Pulse Width	5		110	250	1
Clock twh	10	_	45	100	
	15	_	35	75	1
	5		100	200	1
Clear	10		40	80	1
	15		30	60	
	5	2	4.5	_	1
Maximum Clock Frequency fcL	10	5	11	l	I мн₂
	15	6.5	14		"""
The state of the s	5	15	1		1
Maximum Clock Rise or Fall Time trCL, trCL	10	15	1 _		μs
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	15	15	_	_	~
· · · · · · · · · · · · · · · · · · ·	5		60	120	1
Minimum Data Setup Time tsu	10		25	50	1
	15	_	20	40	1
	5		40	80	1
Minimum Data Hold Time th	10	_	20	40	ns
till the same in the same same same same same same same sam	15	_	15	30	
	5		125	250	┥
Minimum Clear Removal Time ‡ trem	10		50	100	
them	15		40	80	ł
Innut Occasions	19	<del></del>			
Input Capacitance CIN	_	_	5	7.5	pF

### ‡ CLEAR signal must be high prior to positive-going transition of CLOCK pulse.

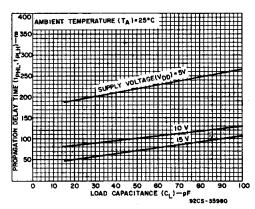


Fig. 3 - Typical propagation delay time (CLOCK to OUTPUT) as a function of load capacitance.

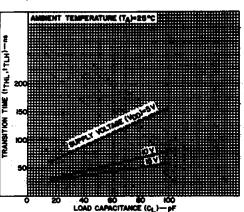


Fig. 4 – Typical transition time as a function of load capacitance.

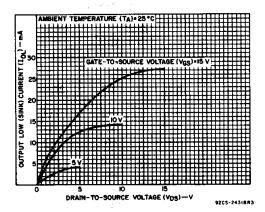


Fig. 5 – Typical output low (sink) current characteristics.

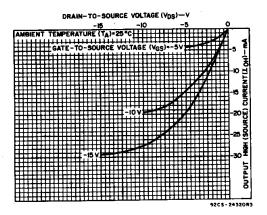


Fig. 7 - Typical output high (source) current characteristics.

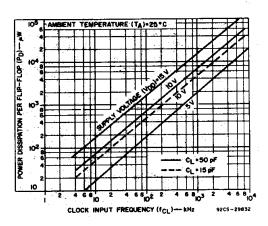


Fig. 9 – Typical dynamic power dissipation as a function of CLOCK frequency.

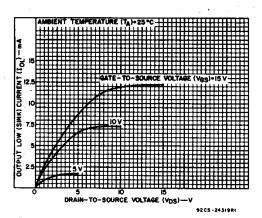


Fig. 6 - Minimum output low (sink) current characteristics.

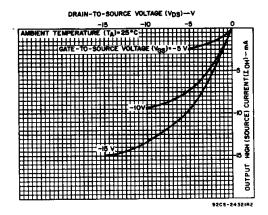


Fig. 8 - Minimum output high (source) current characteristics.

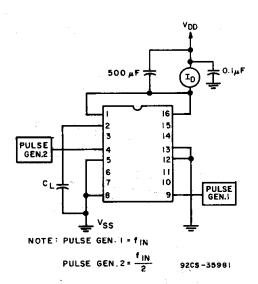
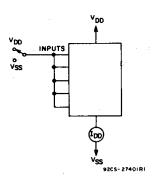


Fig. 10 - Dynamic power dissipation test circuit.



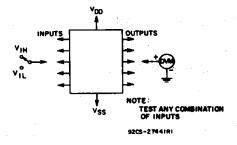


Fig. 11 - Quiescent device current test circuit.

Fig. 12 - Noise immunity test circuit.

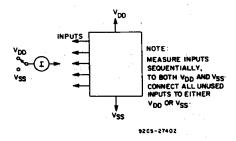
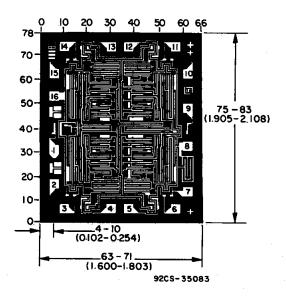


Fig. 13 - Input leakage current test circuit.



Dimensions and pad layout for CD40175BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).

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PRODUCT FOLDER | PRODUCT INFO: FEATURES | DESCRIPTION | DATASHEETS | PRICING/AVAILABILITY/PKG |
APPLICATION NOTES | RELATED DOCUMENTS

PRODUCT SUPPORT: TRAINING

CD40175B, CMOS Quad D-Type Flip-Flop

DEVICE STATUS: ACTIVE

PARAMETER NAME CD40175B
Voltage Nodes (V) 5, 10, 15

FEATURES ABack to Top

- 100% tested for quiescent current at 20 V
- Maximum input current of 1 uA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) =

1 V at  $V_{DD} = 5 \text{ V}$ 

2 V at  $V_{DD} = 10 \text{ V}$ 

 $2.5 \text{ V} \text{ at } V_{DD} = 15 \text{ V}$ 

- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"
- Output compatible with two HTL loads, two low power TTL loads, or one low power Schottky TTL load
- Functional equivalent to TTL74175
- Standardized, symmetrical output characteristics
- Applications:
  - Shift registers
  - Buffer/storage registers
  - Pattern generators

DESCRIPTION ABACK to Top

Cd40175B consists of four identical D-type flip-flops. Each flip-flop has an independent DATA D input and complementary Q and Q\ outputs. The CLOCK and CLEAR inputs are common to all flip-flops. Data are transferred to the Q outputs on the positive-going transition of the clock pulse. All four flip-flops are simultaneously reset by a low level on the CLEAR input.

These devices can function as shift register elements or as T-type flip-flops for toggle and counter applications.

The CD40175B is supplied in hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead small-outline package (NSR suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).

TECHNICAL RESOURCES

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DATASHEET

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Full datasheet in Acrobat PDF: cd40175b.pdf (230 KB,Rev.A) (Updated: 03/18/2002)

**APPLICATION NOTES** 

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View Application Reports for Digital Logic

Product Folder: CD40175B, CMOS Quad D-Type Flip-Flop

• Evaluation of Nickel/Palladium/Gold-Finished Surface-Mount Integrated Circuits (SZZA026 - Updated: 06/20/2001)

#### RELATED DOCUMENTS

Back to Top

- Advanced Bus Interface Logic Selection Guide (SCYT126, 448 KB Updated: 01/09/2001)
- Documentation Rules (SAP) And Ordering Information (Rev. B) (SZZU001B, 13 KB Updated: 05/06/1999)
- Logic Selection Guide First Half 2002 (Rev. Q) (SDYU001Q, 3368 KB Updated: 12/17/2001)
- MicroStar Junior BGA Design Summary (SCET004, 167 KB Updated: 07/28/2000)
- More Power In Less Space Technical Article (Rev. A) (SCAU001A, 850 KB Updated: 03/01/1996)
- Overview of IEEE Std 91-1984, Explanation of Logic Symbols Training Booklet (Rev. A) (SDYZ001A, 138 KB Updated: 07/01/1996)

PRICING/AVAILA	PRICING/AVAILABILITY/PKG  Back to Top									
ORDERABLE DEVICE	PACKAGE	PINS	TEMP (°C)	<u>STATUS</u>	BUDGETARY PRICE USS/UNIT QTY=1000+	PACK QTY	DSCC NUMBER	PRICING/AVAILABILITY/PKG		
CD40175BE	<u>N</u>	16	-55 TO 125	ACTIVE	0.34	25		Check stock or order		
CD40175BF3A	<u>J</u>	16	-55 TO 125	ACTIVE	2.86	1		Check stock or order		
CD40175BNSR	<u>NS</u>	16	-55 TO 125	ACTIVE	0.55	2000		Check stock or order		
CD40175BPW	<u>PW</u>	16	-55 TO 125	OBSOLETE						
CD40175BPWR	<u>PW</u>	16	-55 TO 125	ACTIVE	0.48	2000		Check stock or order		

Table Data Updated on: 4/28/2002

 $\underline{Products} \mid \underline{Applications} \mid \underline{Support} \mid \underline{TI\&ME}$ 

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